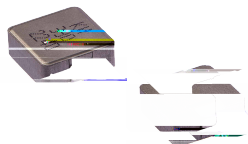




MDA Series

SMD Low Profile High Current Molded Inductor

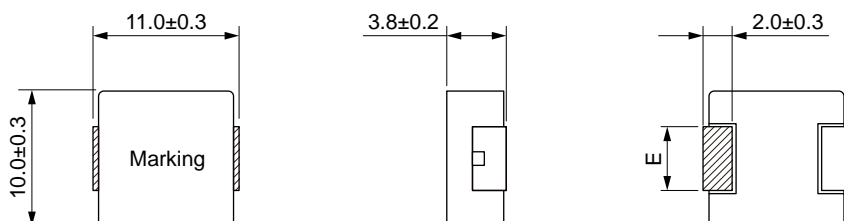
Size 1040



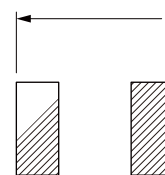
APPLICATION

-
- HVAC
-
- Audio subsystem
- Digital instrument cluster
-

Dimensions: [mm]

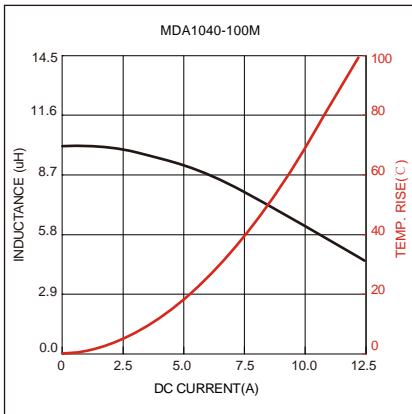
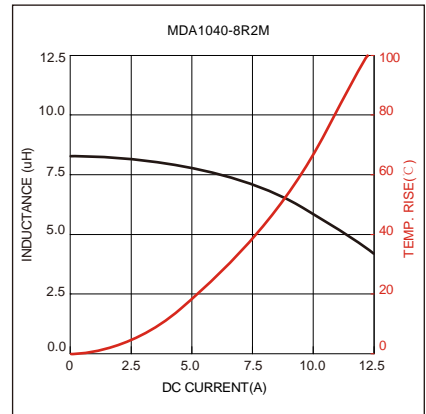
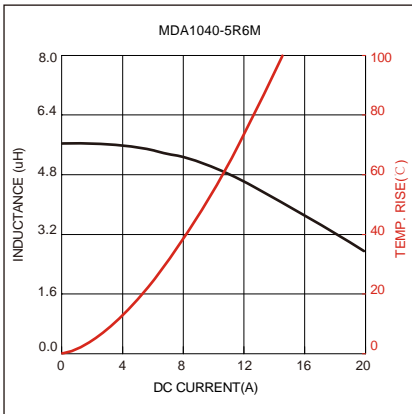
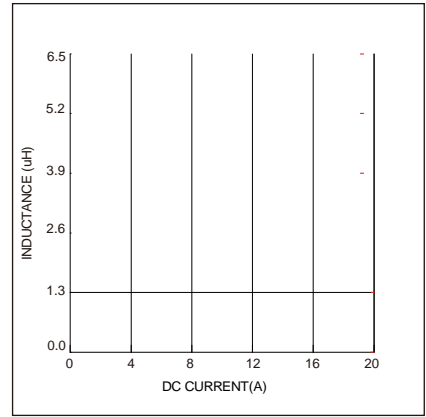
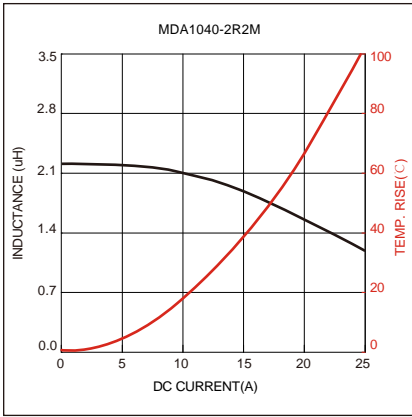


Land Pattern: [mm]

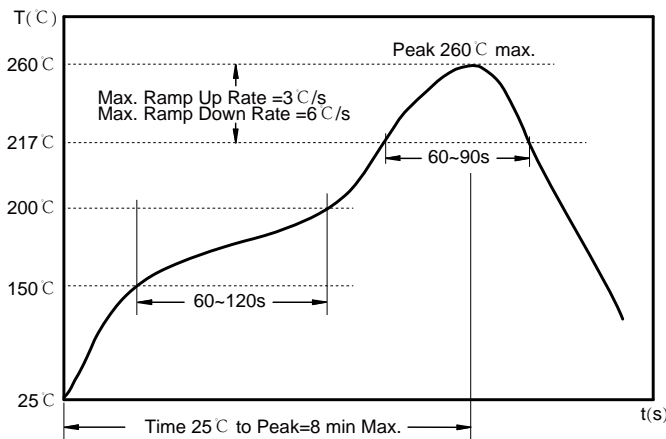


Electrical Properties:

MDA1040-R15N	0.15	±30%	44.0	38.0	82.0	75.0	0.50	0.60	3.0±0.3
MDA1040-R22M	0.22	±20%	36.0	33.0	70.0	60.0	0.72	0.83	3.0±0.3
MDA1040-R36M	0.36	±20%	33.0	29.0	51.0	45.0	1.05	1.18	3.0±0.3
MDA1040-R47M	0.47	±20%	32.0	28.0	46.0	40.0	1.30	1.50	3.0±0.3
MDA1040-R56M	0.56	±20%	25.0	23.0	34.0	29.0	1.60	1.80	2.5±0.3
MDA1040-R68M	0.68	±20%	23.0	20.0	31.0	28.0	1.90	2.20	2.5±0.3
MDA1040-1R0M	1.00	±20%	20.0	18.0	29.0	26.0	2.90	3.25	2.5±0.3
MDA1040-1R5M	1.50	±20%	17.5	16.0	26.0	22.0	3.70	4.20	2.5±0.3
MDA1040-1R8M	1.80	±20%	16.5	15.0	23.0	20.0	5.10	5.70	3.0±0.3
MDA1040-2R2M	2.20	±20%	15.0	13.0	20.0	16.0	5.80	6.70	3.0±0.3
MDA1040-3R3M	3.30	±20%	11.0	10.0	17.5	14.0	10.5	11.8	3.0±0.3
MDA1040-4R7M	4.70	±20%	8.80	8.0	15.2	13.0	15.8	19.0	3.0±0.3
MDA1040-5R6M	5.60	±20%	8.00	7.2	14.1	11.5	19.0	22.8	3.0±0.3
MDA1040-6R8M	6.80	±20%	7.80	6.8	12.2	11.0	22.0	24.5	3.0±0.3



Soldering Reflow:



Preheat condition: 150 ~200°C / 60~120 sec.

Allowed time above 217°C : 60~90 sec.

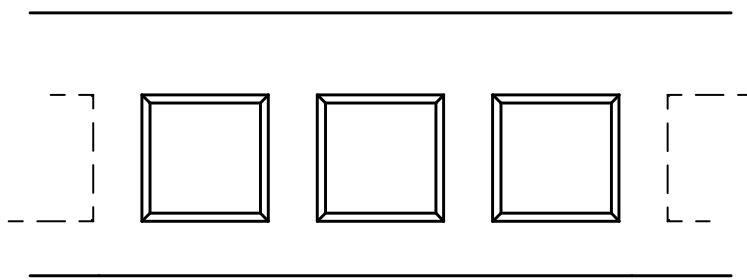
Max temperature: 260°C .

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

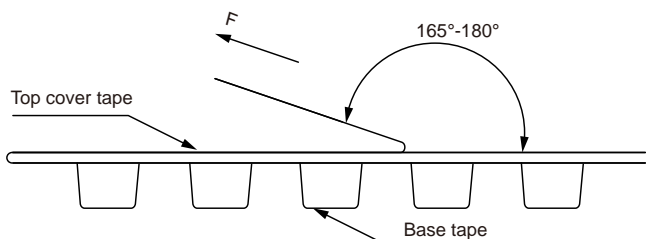
Packaging Information:

Tape Dimension :



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA1040	10.4±0.1	11.6±0.1	1.5±0.1	4.0±0.1	16.0±0.1	24.0±0.3	4.3±0.1	1.75±0.1	0.35±0.05

Peel force of top cover tape:



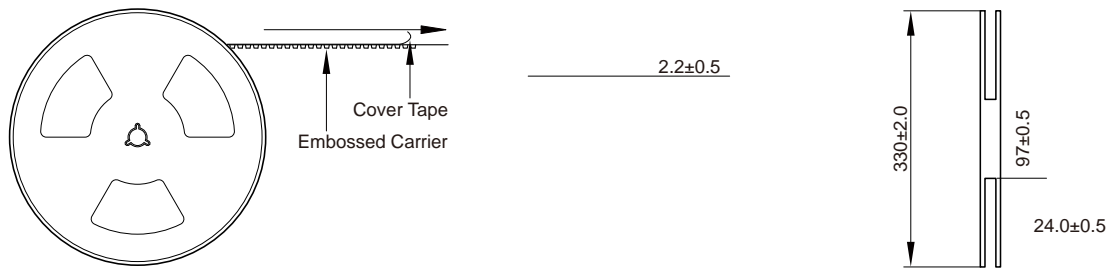
The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

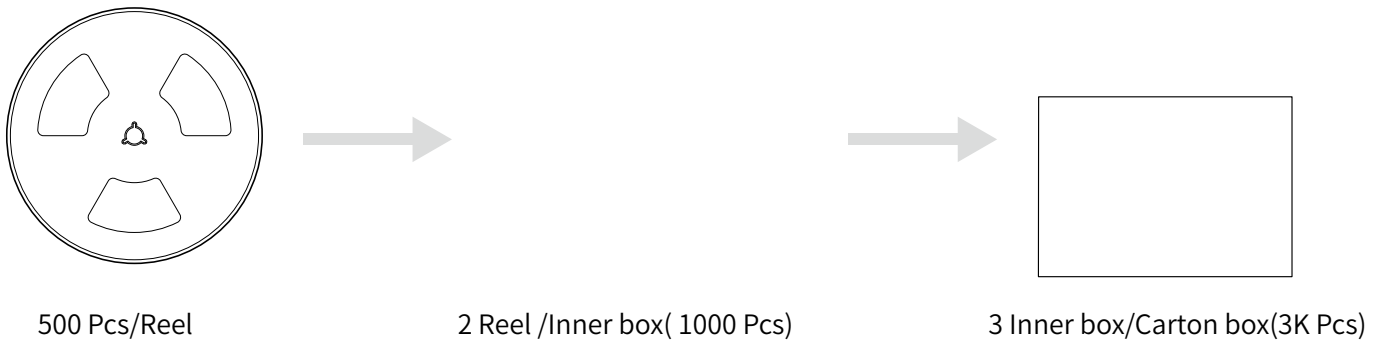
Marking	KH+Printing (Inductance+period)



Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions:

Operation Instructions: